

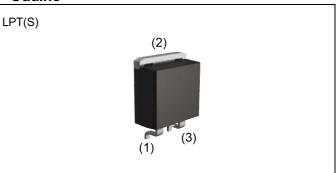
1) Fast reverse recovery time (trr)

4) Drive circuits can be simple

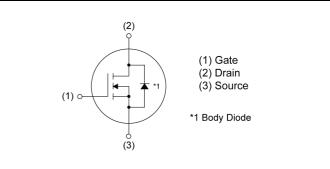
5) Pb-free plating ; RoHS compliant

V <sub>DSS</sub>	600V
R <sub>DS(on)</sub> (Max.)	0.585Ω
I <sub>D</sub>	±9A
P <sub>D</sub>	125W

# ●Outline



# Inner circuit



## Application

Features

2) Low on-resistance3) Fast switching speed

Switching

# Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6009JNJ
Quantity (pcs)	1000

# • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	600	V
Continuous drain current ( $T_c = 25^{\circ}C$ )	I <sub>D</sub> *1	±9	А
Pulsed drain current	I <sub>DP</sub> *2	±27	А
Gate - Source voltage	V <sub>GSS</sub>	±30	V
Avalanche current, single pulse	I <sub>AS</sub> *3	1.8	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	177	mJ
Power dissipation $(T_c = 25^{\circ}C)$	P <sub>D</sub>	125	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## Thermal resistance

Deremeter	C: mak al	Values			Lincit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	1.00	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Sumpleal	Conditions	Values			Linit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		600	-	-	V	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	-	-	100	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±30V, $V_{DS}$ = 0V	-	-	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1.38$ mA	5.0	6.0	7.0	V	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 15V, I <sub>D</sub> = 4.5A T <sub>j</sub> = 25°C	-	0.450	0.585	Ω	
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	2.1	-	Ω	



## • Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Cumph of	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	645	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 100V	-	40	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	1.5	-	_
Effective output capacitance energy related	C <sub>o(er)</sub> <sup>6</sup>	V <sub>GS</sub> = 0V	-	32	-	pF
Effective output capacitance time related	C <sub>o(tr)</sub> <sup>7</sup>	$V_{DS} = 0V$ to 480V	-	120	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 300$ V, $V_{GS}$ = 15V	-	20	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 4.5A	-	16	-	20
Turn - off delay time	$t_{d(off)}^{*5}$	$R_L \simeq 68.1\Omega$	-	38	-	ns
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	20	-	

# • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Cumphal	Conditions	Values			Unit
Parameter	arameter Symbol Conditions		Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	$V_{DD} \simeq 300 V$	-	22.0	-	
Gate - Source charge	$Q_{gs}^{*5}$	I <sub>D</sub> = 9A	-	6.4	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*5}$	V <sub>GS</sub> = 15V	-	8.0	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 300V$ , $I_D = 9A$	-	9.2	-	V

\*1 Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  100mH, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , starting T<sub>i</sub> = 25°C

- \*4 Tc=25°C
- \*5 Pulsed
- \*6 Co(er) is a fixed capacitance that gives the same stored energy as Coss while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .
- \*7 Co(tr) is a fixed capacitance that gives the same charging time as Coss while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .

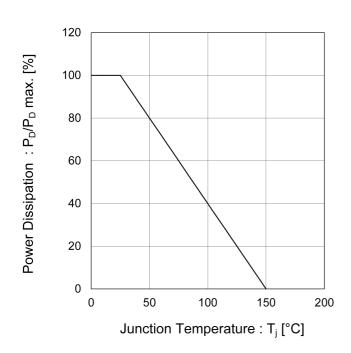


## •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Source current	I <sub>S</sub> *1		-	-	9	А
Pulsed source current	$I_{SP}^{*2}$	T <sub>C</sub> = 25°C	-	-	27	А
Source-Drain voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 9A	-	-	1.7	V
Reverse recovery time	t <sub>rr</sub> *5		-	65	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	I <sub>S</sub> = 9Α di/dt = 100Α/μs	-	195	-	nC
Peak reverse recovery current	۲ <mark>, *</mark> 5		-	7.0	-	А







# Fig.1 Power Dissipation Derating Curve

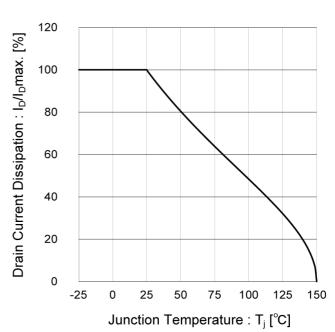


Fig.2 Drain Current Derating Curve vs. Junction Temperature

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

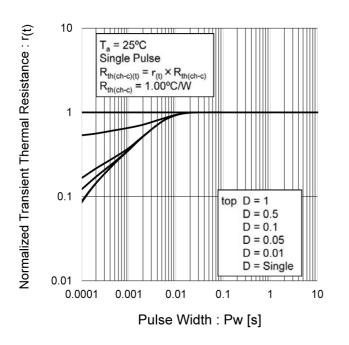
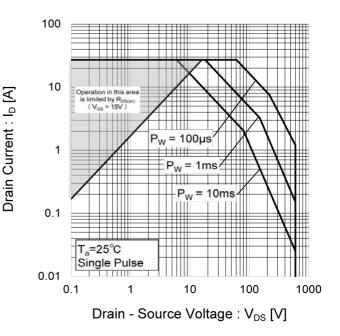


Fig.4 Maximum Safe Operating Area





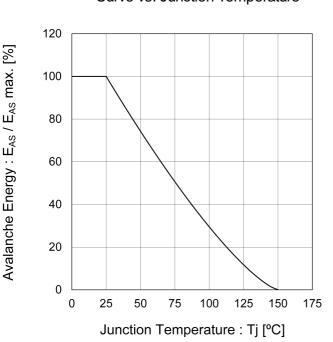




Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

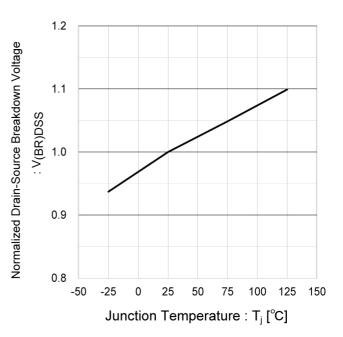


Fig.7 Typical Output Characteristics(I)

Drain Current : I<sub>D</sub> [A]

1

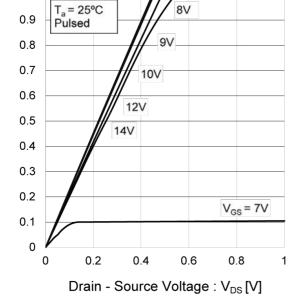
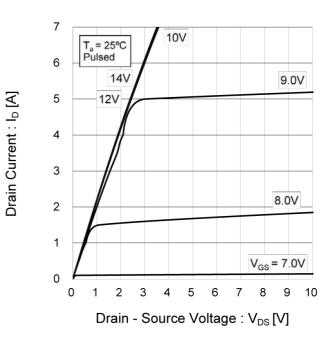
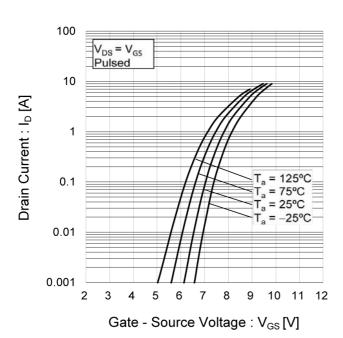


Fig.8 Typical Output Characteristics(II)







## Fig.9 Typical Transfer Characteristics

Fig.10 Normalized Gate Threshold . Voltage vs Junction Temperature

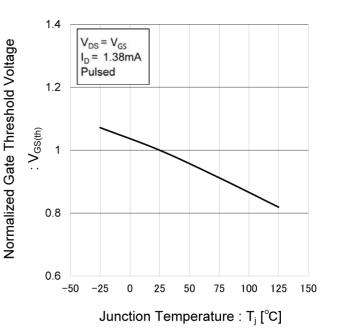
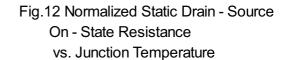
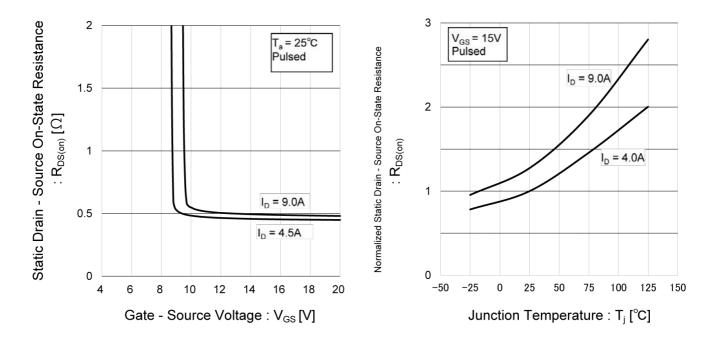


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage







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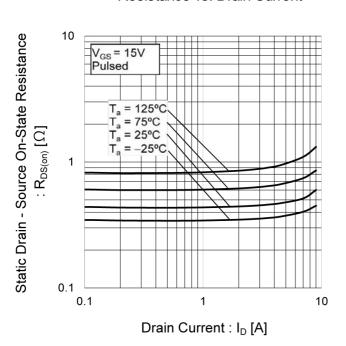


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current

Fig.14 Typical Capacitance vs. Drain - Source Voltage

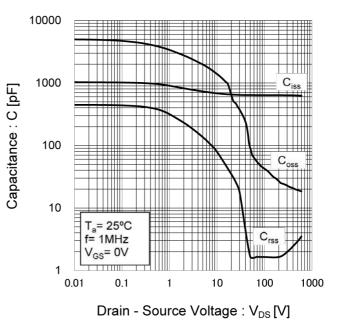
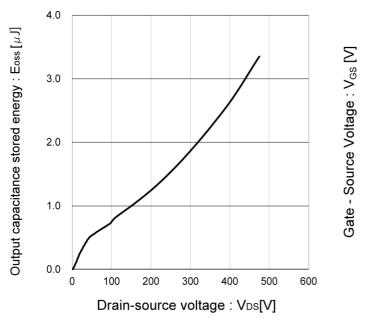
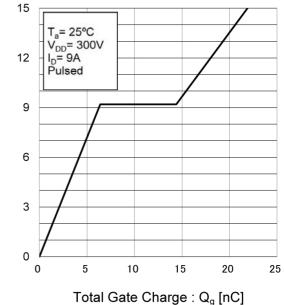


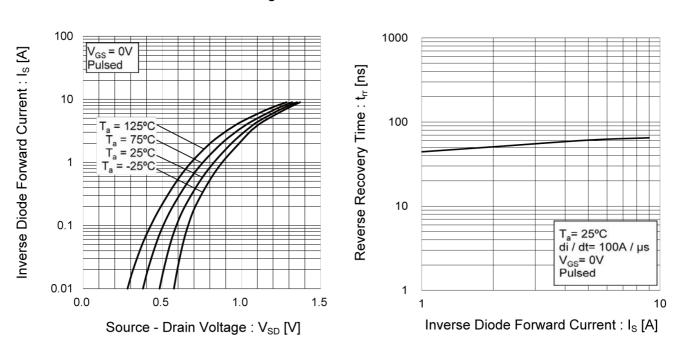
Fig.15 Typical Coss Stored Energy

Fig.16 Typical Gate Charge

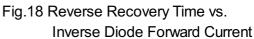








# Fig.17 Inverse Diode Forward Current vs. Source - Drain Voltage

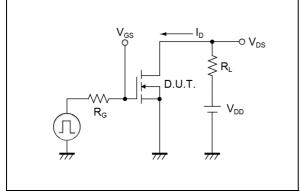




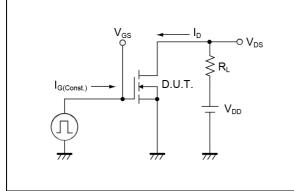


## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit



#### Fig.2-1 Gate Charge Measurement Circuit



### Fig.3-1 Avalanche Measurement Circuit

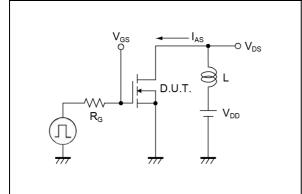
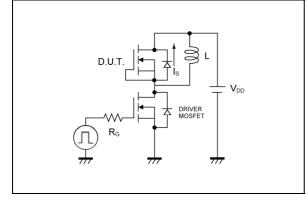
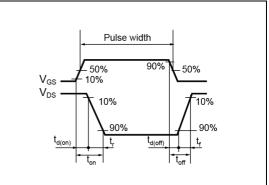


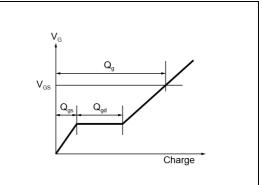
Fig.4-1 Diode Recovery Measurement Circuit



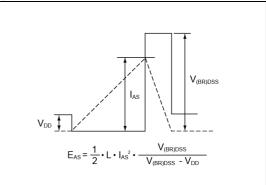
## Fig.1-2 Switching Waveforms



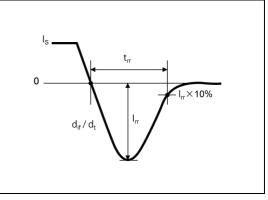
#### Fig.2-2 Gate Charge Waveform



### Fig.3-2 Avalanche Waveform

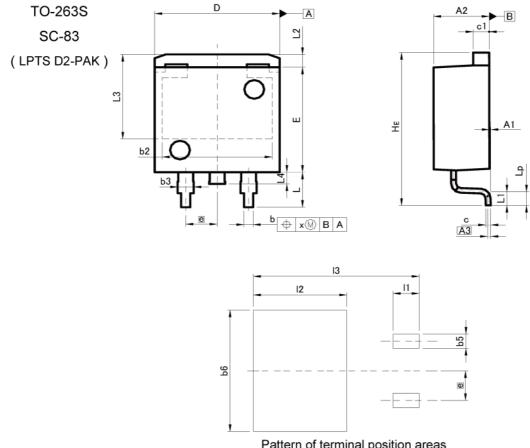


### Fig.4-2 Diode Recovery Waveform





## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
A1	0.00	0.30	0.000	0.012		
A2	4.30	4.70	0.169	0.185		
A3	0.	25	0.0	10		
b	0.68	0.98	0.027	0.039		
b2	8.	90	0.3	50		
b3	1.14	1.44	0.045	0.057		
C	0.30	0.60	0.012	0.024		
c1	1.10	1.50	0.043	0.059		
D	9.80	10.40	0.386	0.409		
E	8.80	9.20	0.346	0.362		
e	2.	2.54		00		
HE	12.80	13.40	0.504	0.528		
L	2.70	3.30	0.106	0.130		
L1	1.	1.20		0.047		
L2	1.	10	0.043			
L3	7.	25	0.285			
L4	1.	00	0.0	39		
Lp	0.90	1.50	0.035	0.059		
x	<b>Z</b> .	0.25		0.010		
	MILIM	ETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
b5	<del>.</del>	1.23	-	0.049		
b6		10.40		0.409		
11	<u></u>	2.10	1 <u>111</u>	0.083		
12		7.55	1. 1.	0.297		
13	<del></del>	13.40		0.528		

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
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CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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